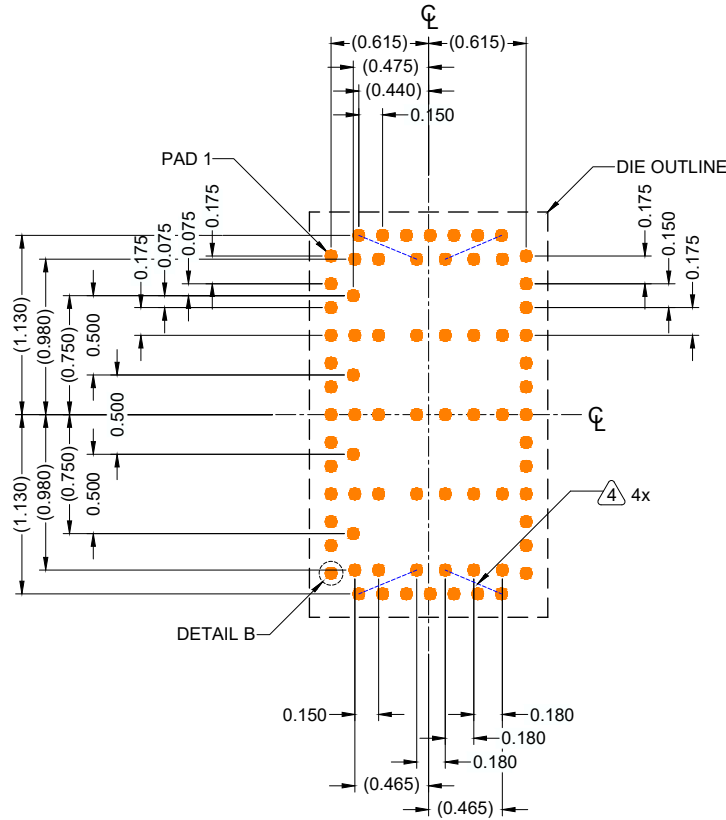
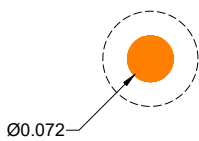


NOTES:

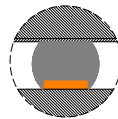
1. All dimensions are in millimeters (mm) and angles are in degrees
2. Tolerances of ± 0.007 mm apply to untoleranced dimensions
3. Dimensions in parenthesis () are for reference only



RECOMMENDED LAND PATTERN
(Substrate Top View, NSMD Design)



DETAIL B



SIDE VIEW CROSS-SECTION OF BUMP ON PAD FROM DETAIL B

NOTES:

1. All dimensions are in millimeters (mm) and angles are in degrees.
2. Land Pattern exhibits substrate pads for die bump connections.
3. A complete layout requires additional connections and ground patterns.
- ④ Substrate circuit requires networks for redundant die bump connections.
Land pattern identifies pads to connect, but layout details are not shown.